# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs  

**Marketing Name / Model**  
[List multiple models if applicable.]  

HP Spectre XT TouchSmart

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.  
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>screw driver</td>
</tr>
<tr>
<td>Description #2</td>
<td>screw driver</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove log low
2. remove battery pack
3. remove LCD Module
4. remove Front Speaker
5. remove DC_IN & Cable and I/O Board
6. remove HDD Module
7. remove Thermal Module
8. remove Card Module
9. remove MB
10. remove Rear Speaker
11. remove TP LED Board
12. remove TP Module
13. remove Antenna
14. remove Power Board
15. remove KB support Brk
16. remove KB
17. remove ESD PCB
18. divide Display assy (remove LCD Bezel)
19. divide Display assy (remove LCD Hinge Cap L-R)
20. divide Display assy (remove LCD module)
21. divide Display assy (remove LCD Hinge Brk L-R)
22. divide Display assy (remove LVDS Cable & control board cable)
23. divide M/B assy (remove Rj45 Door ASSY)
24. divide M/B assy (remove Shielding can ASSY_TOP)
25. divide MB assy (remove RTC Battery)
26. divide MB assy (Shielding can ASSY_BTM)
27. divide Display assy (remove LCD cover AL skin)
28. divide Log UP assy (remove Log up AL skin)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove log low
Step 2 Remove Battery pack

Step 3 Remove LCD Module.
Step 4 Remove Front Speaker

Step 5 Remove DC_IN & Cable and I/O Board
Step 6 Remove HDD Module.
Step 7: Remove Thermal Module.

Step 8: Remove Card Module

Step 9: Remove MB

Step 10: Remove Rear Speaker

Step 11: Remove TP LED Board

Step 12: Remove TP Module

Step 13: Remove Antenna

Step 14: Remove Power Board
Step 15 Remove KB support Bracket

Step 16 Remove KB

Step 17 Remove ESD PCB

Step 18 divide Display assy (remove LCD Bezel)

Step 19 divide Display assy (remove LCD Hinge Cap L-R)

Step 20 divide Display assy (remove LCD module)

Step 21 divide Display assy (remove LCD Hinge Brk L-R)
Step 22 divide Display assy (remove LVDS Cable & control board cable)

Step 23 divide M/B Assy (remove RJ 45 Door ASSY)

Step 24 divide M/B Assy (Shielding can ASSY_TOP)

Step 25 divide MB Assy (remove RTC Battery)

Step 26 divide MB Assy (Shielding can ASSY_BTM)
Step 27 divide Display assy (remove LCD cover AL skin)

Step 28 divide Log UP assy (remove Log up AL skin)